

09/17625



U.S. UTILITY Patent Application

O.I.P.E	PATENT DATE
1A SCANNED <i>NSC 3</i> G.A.	<i>EW</i>

APPLICATION NO. 09/762,582	CONT/PRIOR D F	CLASS 205	SUBCLASS 126	ART UNIT. 1741	EXAMINER Smith, H. D.
-------------------------------	-------------------	--------------	-----------------	-------------------	--------------------------

APPlicants

Akihisa Hongo
Naoya Ogura
Hiroaki Inoue
Satōshi Isomura

Wafer plating method and apparatus

TITLE

- 2 -

PTO-2040
12/99

ISSUING CLASSIFICATION

Continued on Issue Slip Inside File-jacket

<input checked="" type="checkbox"/> TERMINAL DISCLAIMER		DRAWINGS			CLAIMS ALLOWED	
<input checked="" type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.		Sheets Drwg. Figs. Drwg. Print Fig.			Total Claims Print Claim for O.G.	
<input checked="" type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____.		Assistant Examiner _____ (Date)			NOTICE OF ALLOWANCE MAILED	
<input checked="" type="checkbox"/> The terminal disclaimer of this patent have been disclaimed.		Primary Examiner _____ (Date)			ISSUE FEE	
					Amount Due	Date Paid
					ISSUE BATCH NUMBER	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 161 and 363. <small>Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.</small>						

WARNING

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35 Sections 122, 181, and 363.
Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form PTO-438A
(Rev. 8/89)

FILED WITH: DISK (CBF) FICHE CD-ROM

www.3d-kom.de